

Serial Number: unassigned

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Title: DIRECT BUILD-UP LAYER ON AN ENCAPSULATED DIE PACKAGE HAVING A MOISTURE BARRIER  
STRUCTURE

Assignee: Intel Corporation

REMARKS

Claims 5-19 are canceled by this amendment. Claims 1-4 and 20-34 are currently pending. No new matter has been added by this amendment.

Conclusion

Applicant considers the divisional application in condition for examination, and earnestly requests the prompt examination thereof. The Examiner is invited to telephone Applicant's attorney, John Greaves at (801) 278-9171 or the below signed attorney to facilitate prosecution of this application.

If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743

Respectfully submitted,

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Feb. 6, 2004

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